

SDIA6020 TYPE

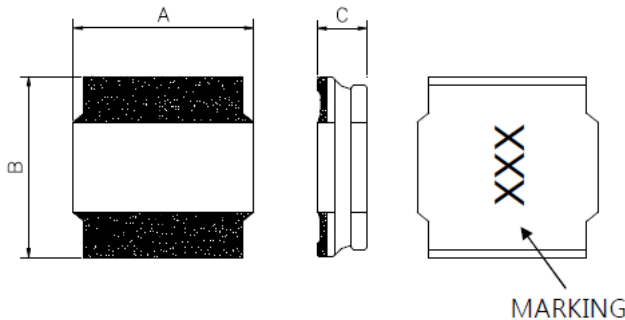
●FEATURE

1. Low profile (Height: 2.00mm Max)
2. Low DC resistance

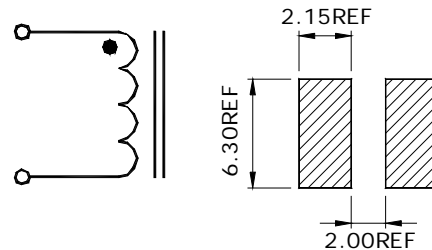
●Applications

1. Digital camera , PDA and others

●Shape and Dimension



●Schematics and Land Patterns(mm)



A=6.00±0.40m/m ; B=6.00±0.40m/m ; C=2.00m/m Max.

●Specification

Part Number	L(uH)	Marking	DCR(mΩMax)	Isat(A)	Irms(A)
SDIA6020-0R8N	0.8±30%	0R8	26.0	5.50	3.80
SDIA6020-1R0N	1.0±30%	1R0	30.0	4.20	3.30
SDIA6020-1R5N	1.5±30%	1R5	33.8	4.00	3.20
SDIA6020-2R2M	2.2±20%	2R2	44.2	3.20	2.70
SDIA6020-3R3M	3.3±20%	3R3	52.0	2.80	2.60
SDIA6020-4R7M	4.7±20%	4R7	75.4	2.40	2.00
SDIA6020-6R8M	6.8±20%	6R8	110.5	2.00	1.80
SDIA6020-100M	10±20%	100	162.5	1.70	1.40
SDIA6020-150M	15±20%	150	220.0	1.10	1.00
SDIA6020-220M	22±20%	220	377.0	1.05	0.95

Note1. Measurement frequency of Inductance value : at 100KHz

Note2. Measurement ambient temperature of L, DCR and IDC : at 25°C

Note3. Inductance Tolerance: M : ±20% ; N : ±30%

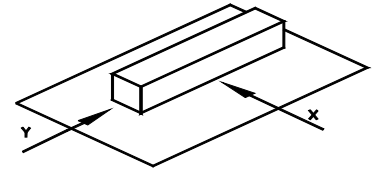
Note4. Isat : $\Delta L/L \leq 30\%$ (This indicates the value of current when the inductances is 30% lower than its initial value at D.C. superimposition)

Note5. Irms:D.C. current when at $\Delta t=40^\circ\text{C}$ (typ.).($T_a=25^\circ\text{C}$)

GENERAL CHARACTERISTICS

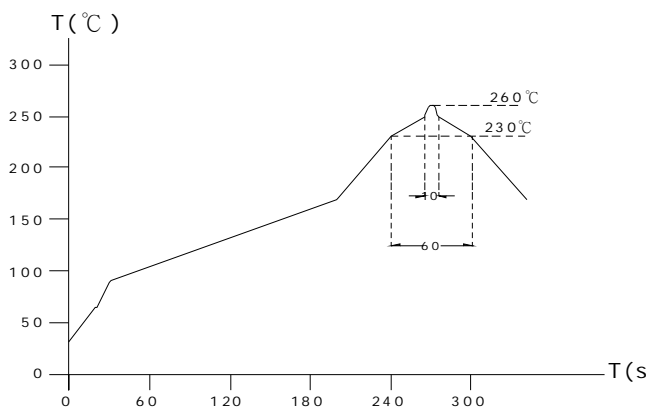
1. Operating temperature range: -40 TO + 105°C (Includes temperature when the coil is heated)
2. External appearance: On visual inspection, the coil has no external defects.
3. Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Ywithstanding at below conditions.

Terminal should not peel off. (refer to figure at right) 5. 0N 60 sec.



4. Insulating resistance: Over 100MΩ at 100V D.C. between coil and core.
5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core.
6. Temperature characteristics: Inductance coefficient $(0\sim 2,000)\times 10^{-6}/^{\circ}\text{C}$ (-25~+80°C).
7. Humidity characteristics(Moisture Resistance): Inductance deviation within $\pm 5\%$, after 96 hours in 90~95% relative humidity at $40 \pm 2^{\circ}\text{C}$ and 1 hour drying under normal condition.
8. Vibration resistance: Inductance deviation within $\pm 5\%$, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.
9. Shock resistance: Inductance deviation within $\pm 5\%$, after being dropped once with 981m/s² (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
10. Resistance to Soldering Heat: 260°C, 10 seconds(See attached recommend reflow)
11. Storage environment: Storage condition: Temperature Range: 10°C ~ 35°C (Generally: 21°C ~ 31°C) , Humidity Range: 50% ~ 80% RH (Generally: 65% ~ 75%) ; Transportation condition: Temperature Range: -35°C ~ 85°C , Humidity Range: 50% ~ 95% RH
12. Use components within 12 months. If 12 months or more have elapsed, check solderability before use.
13. Reflow profile recommend:

Lead-free heat endurance test



Lead-free the recommended reflow condition

